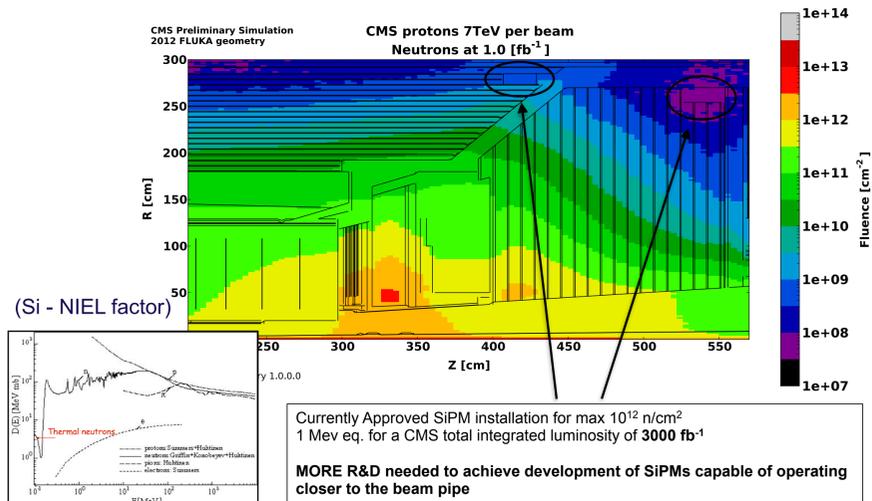


Effects of Very High Radiation on SiPMs

A. Heering¹⁾, Y. Musienko^{1*)}, M. Wayne¹⁾, R. Ruchti¹⁾

¹⁾University of Notre Dame, * On leave from INR (Moscow)

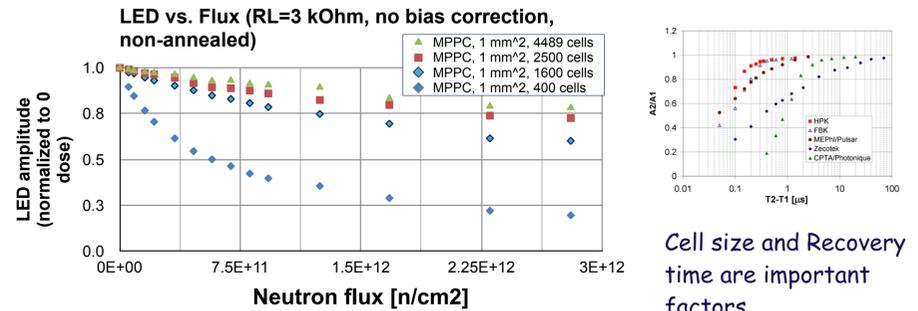
Radiation Damage in CMS



Three Data Sets

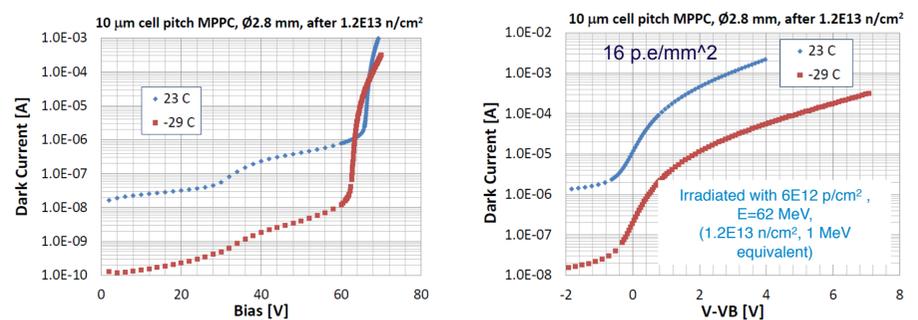
Radiation Damage test up to $3 \cdot 10^{12}$ n/cm²

Cern irradi 6 Neutrons from backscattered protons (2010)



Radiation Damage test to $1 \cdot 10^{13}$ 1MeV eq n/cm²

LIF at UCL Belgium (2014)



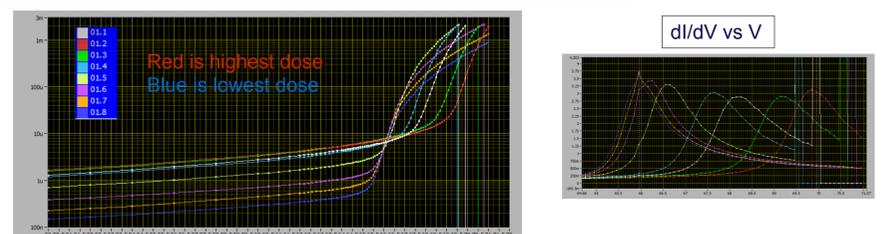
Noise in 25 ns is 16 p.e. and 2.6 p.e./mm² at Vb =3V at resp. 23C and -29 C

Radiation Damage test up to $1.3 \cdot 10^{14}$ p/cm²

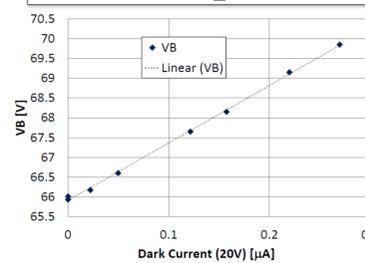
CERN 23 GeV proton Beam (2015)

- HPK 6 mm² 10 micron cell with different dose (8 channel array ; Ch 2 in full beam ; Ch 8 farthest away from beam)

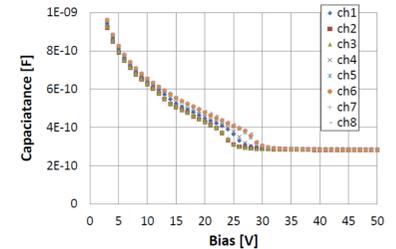
Leakage currents after radiation show large shift in Break down voltage



Linear Behavior of V_{breakdown} vs dose



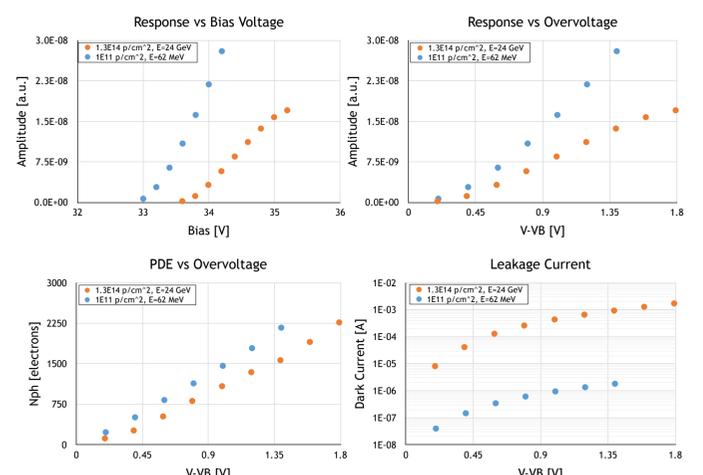
HPK 10 micron array after 1E14 p/cm²



- FBK 1 mm² 12 micron cell with thin epitaxial layer

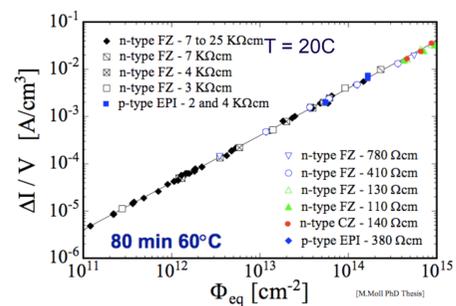
Measured at T= 23 Celsius

- Small bias shift of 0.5V
- Low PDE change
- Dark current 1 mA/mm²
- Gain reduction due to self heating of the device



Theory vs measurement

Leakage current increase in Si-PIN diodes for 1 MeV equivalent dose



Similar damage seen in GM-APDs or SiPMs

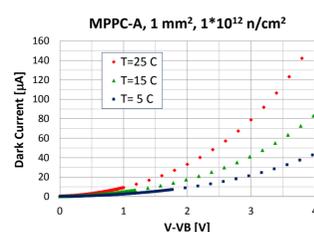
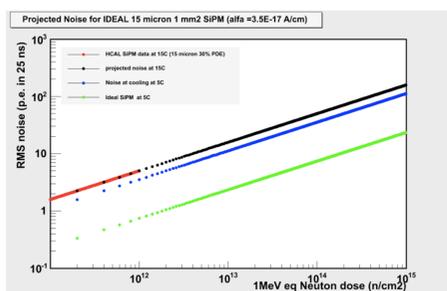
slope = $3.5E-17$ A/cm
V = cell size * d_{epi} (few microns)

Due thin epitaxial layer SiPMs are intrinsically radiation harder than PIN diodes

Due to high gain we can see the current increase in SiPMs as single p.e. counts:

$$\text{Dark Count} = 1/q * V * \Phi * \text{slope} * G.F. * P(V)$$

Measurements show 4X more noise

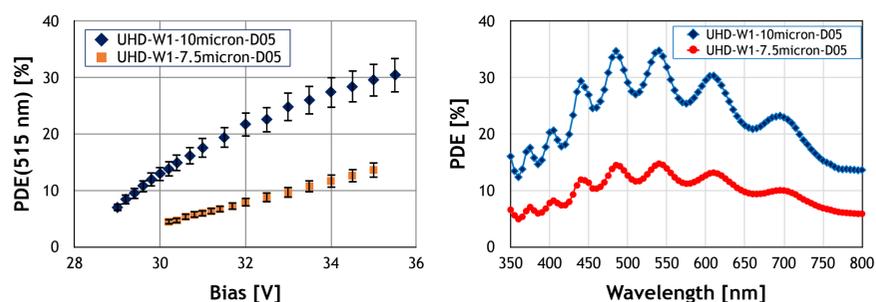


During R&D for the CMS HCAL Phase I Upgrade, we found that the dark noise generation rate in APDs/SiPMs is dominated by high electric field effects (mainly by tunneling via radiation-induced defects in Si) as well as by cell edge effects. Modification of electric field profile of the SiPM's p-n junction and cell periphery may help to reduce these effects.

Current R&D with FBK

Ultra high density cells with trench technology

First results of SiPMs with 7.5 micron show good PDE due to IRST - FBKs advanced trench technology



Combined effort between FBK and CMS looks very promising. We hope to further reduce gain and field effect tunneling in future R&D wafer runs to increase radiation hardness